



## T-Series IGBT Modules – NX-Type

The Mitsubishi Electric 7<sup>th</sup> Generation NX-Type IGBTs greatly simplify the design of medium power inverters for various applications like industrial drives, wind power, solar power and UPS. Features such as an industry standard low profile package, significantly improved thermal impedance and very low loss, 7<sup>th</sup> Generation CSTBT™ technology facilitate a very efficient, economical and robust inverter design.

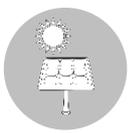
The NX-Type line-up has been expanded up to 1000A/1200V and all new 1700V and 650V line-up of dual modules to suit a wider power range of applications. Design effort is minimized as the 7<sup>th</sup> Generation NX-Type employs the same standard packaging and features previously introduced for the 5<sup>th</sup> and 6<sup>th</sup> Generation NX-Type. The newly developed SLC-Technology of the 7<sup>th</sup> Generation NX-Type enables the design of inverters with higher output current, higher power density and improved reliability in both power and temperature cycling.

Product Advantages	User benefits	Achieved by
<ul style="list-style-type: none"> <li>❑ Low-loss 7<sup>th</sup> generation CSTBT™</li> <li>❑ SLC package technology</li> <li>❑ <math>T_{j,max}</math> of 175°C for switching operation</li> <li>❑ High power density</li> <li>❑ Superior thermal cycling capability</li> <li>❑ Low-profile package</li> <li>❑ Integrated Thermistor</li> </ul>	Extended module life time	<ul style="list-style-type: none"> <li>• Highest thermal cycling capability by Insulated Metal Baseplate (IMB)</li> </ul>
	Reduction of assembly costs	<ul style="list-style-type: none"> <li>• Optional PressFit terminals</li> <li>• production lot-independant paralleling capability</li> </ul>
	Compactness and extended power range	<ul style="list-style-type: none"> <li>• Low loss 7th gen. Chipset</li> <li>• Low thermal resistance <math>R_{th(j-c)}</math></li> <li>• Reduced package inductance by single pattern layout</li> </ul>
	Scalability of power classes	<ul style="list-style-type: none"> <li>• full power rating line-up of 650V, 1200V and 1700V modules</li> </ul>

Circuit	Topology	Package outline	Package size	650V	1200V	1700V
2in1	D		62mm x 152mm	300A	225A	225A
				450A	300A	300A
6in1	T		62mm x 122mm	600A	450A	450A
					800A	600A
					1000A	600A
7in1	R		62mm x 122mm	100A	100A	100A
				150A	150A	150A
				200A	200A	
CIB	M		45mm x 107.5mm	50A	35A	
				75A	50A	
			62mm x 122mm	100A	75A	
					75A	
					100A	100A
	150A	150A				



Industrial



Solar



Wind



Power  
Transmission

## SLC (SoLid Cover)-Technology

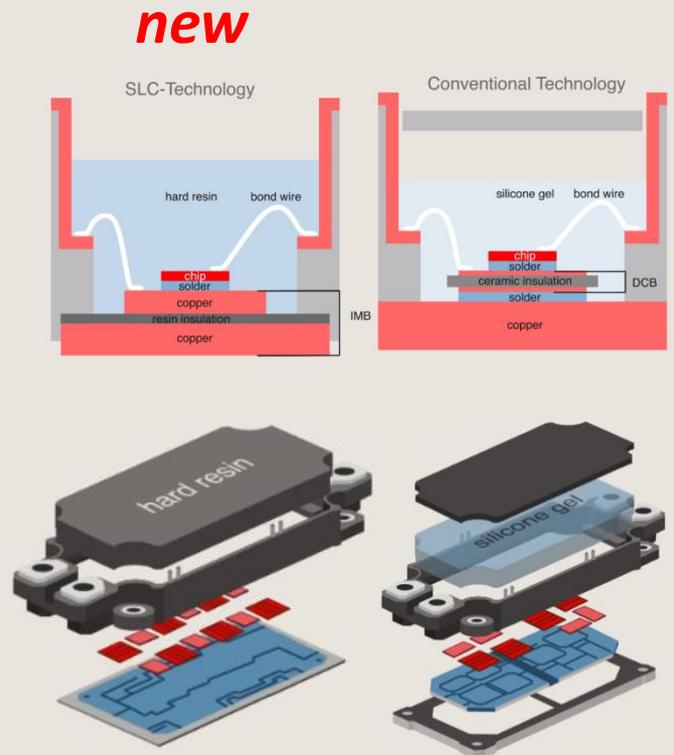
SLC-Technology is a newly developed package technology combining a resin-insulated metal baseplate and hard direct potting resin.

The **IMB** (Insulated Metal Baseplate) combines an electrically insulating resin layer with a top and bottom side copper layer by direct bonding, thus eliminating the substrate solder layer and the baseplate.

Less layers and matched thermal expansion coefficients lead to high thermal cycling capability, exceeding several times the conventional capability. At the same time, the thermal resistance at same chip size is reduced by 30% compared to conventional modules having Aluminium-Oxide insulation.

The SLC concept utilizes one common substrate instead of multiple ceramic substrates. This approach expands the effective area available for mounting chips and eliminates wire bond interconnections.

The top side circuit pattern thickness could be significantly enlarged. This is reducing the electrical resistance and or allowing to shrink the pattern size. Hence, the IMB is a key element of the SLC-Technology for high power density and low stray inductance.



## User-friendly design features

The NX-Type of 7<sup>th</sup> Generation IGBT modules line-up contains press-fit as well as solder pin types. The newly developed “needle eye”-pin type has a self adjusting shape for easy assembly.



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